

DDR4 SERIES



Features:

- Smaller pitch and lower operating voltage
- Supports faster data rates
- Reduced product width
- Various pin tail lengths for PCB thickness

Overview:

- Complies to new interface standard JEDEC POD12
- Nylon 9T halogen free housing for reflow process
- Matte tin plating on contact soldering area for lead-free soldering process
- Supports module variants in UDIMM, RDIMM and LRDIMM
- Allows module seating plane of 2.4mm Max
- Accepts module thickness of 1.4mm

Applications:

- Storage
- Servers
- Desktops
- Industrial Computers



Ordering Information:

DDR4 - 288 - X - XX - X - X - X - X

Termination		Latch Option	
V	TH type	Blank	Small
S	SMT type	F	Big
Dip Options (Dim A, Dim B, Dim C)		Packing Code	
* TH Type	01 2.10mm, 3.94mm, 1.57mm	T	Soft tray
	02 2.67mm, 3.94mm, 1.57mm	H	Hard tray (only SMT type)
	03 3.95mm, 4.60mm, 2.36mm	Contact Area Plating	
	04 3.18mm, 4.60mm, 2.36mm	0	Gold flash
** SMT Type	01 3.94mm, 1.57mm ***	1	15µ" gold
	02 3.94mm, 1.57mm	2	20µ" gold
	03 4.60mm, 2.36mm ***	3	30µ" gold
	04 4.60mm, 2.36mm	4	3µ" gold over 12µ" PdNi
	05 2.00mm, 1.57mm ***	5	3µ" gold over 27µ" PdNi
	06 2.00mm, 1.57mm	Color of Housing/Latch	
		1	Black/Black
		2	Black/Natural
		3	Natural/Black
		4	Natural/Natural
		5	Blue/Natural
		6	Green/Natural
		7	Blue/Blue

*** TH Type Note:**
Dim A = Pin tail length
Dim B = Board lock length
Dim C = Recommended PCB thickness

**** SMT Type Note:**
Dim A = Board lock length
Dim B = Recommended PCB thickness

***** With Mylar for Pick and Place assembly equipment**



To learn more about DDR4 connectors:

web: amphenolcanada.com

email: sales@amphenolcanada.com

Technical Characteristics:

Mechanical	
Insertion Force	10.88Kgf max.
Withdrawal Force	14gf min. (per contact pair)
Retention Force	Contact: 0.30Kgf min. Boardlock: 1.36Kgf min.
Durability	Contact resistance: ΔR : 10m Ω max. after test
Vibration, Mechanical Shock	No physical damage Discontinuity < 1 μ s Contact resistance: ΔR : 10m Ω max. after test
Reseating	No damage
Latch Overstress Force	3.5kg min. force held for 10s with no damage
Latch Actuation Force	The force to fully actuate the latch open shall be 4.5kgf max. per latch
Module Rip Out Force	9.1kgf min. retention force of the module in connector with no damage
Retention of Connector to PCB	No lifting of connector from applicable PCB
Insertion Force of Connector into PCB	Total insertion force to be 6.8kgf max.

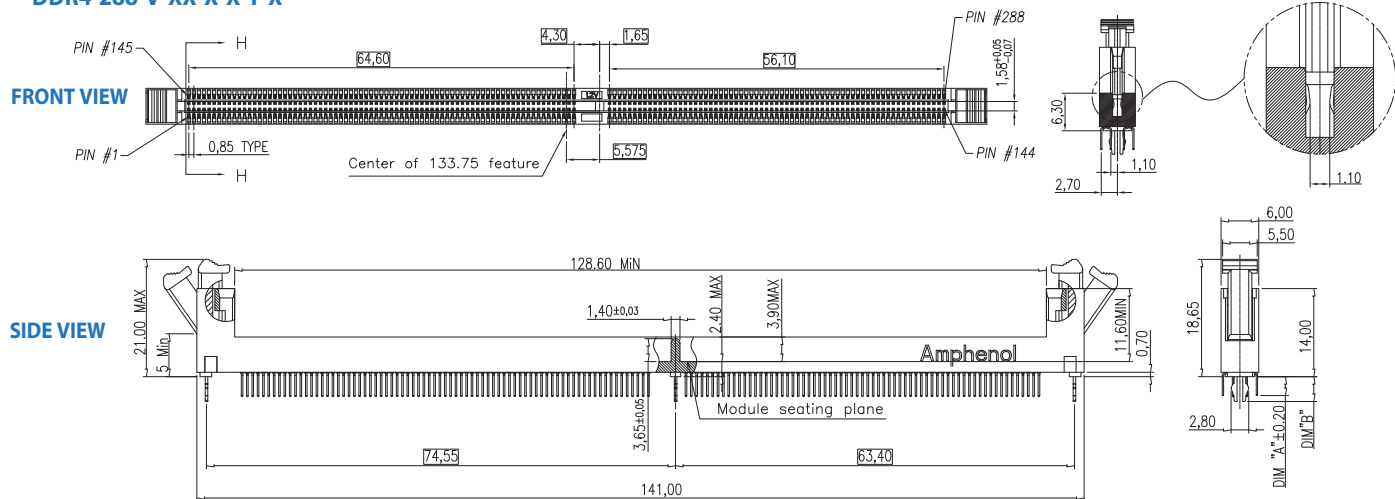
Electrical	
Voltage Rating	30V AC (RMS)/DC
Current Rating	0.7 Amps/pin max.
Low Level Contact Resistance	10m Ω max. initial ΔR : 10m Ω max. after test
DWV	No breakdown
Insulation Resistance	1000 M Ω min.

Materials	
Insulator	High temp. thermal plastic, UL94V-0, Color-option
Contacts	Copper alloy a) Gold flash or b) 15 microinches minimum of gold or c) 30 microinches minimum of gold
Solder Area	Tin or matte tin plating
Underplate	Nickel plating over all
Boardlock	Copper alloy
Solder Area	Tin plating
Underplate	Nickel plating overall

Environmental	
Solderability	Solder coverage: 95% min.
Resistance to Soldering Heat	Visual: no damage or discoloration of connector materials
Temperature Life, Thermal Shock	Contact resistance: ΔR : 10m Ω max. after test
Cycling Temperature and Humidity	Contact resistance: ΔR : 10m Ω max. after test DWV: No breakdown at 500VAC Insulation Resistance: 1000 M Ω min.
Temperature Rise	Temperature rise: 30°C max.
Mixed Flowing Gas, Thermal Disturbance, Salt Spray	Contact resistance: ΔR : 10m Ω max. after test

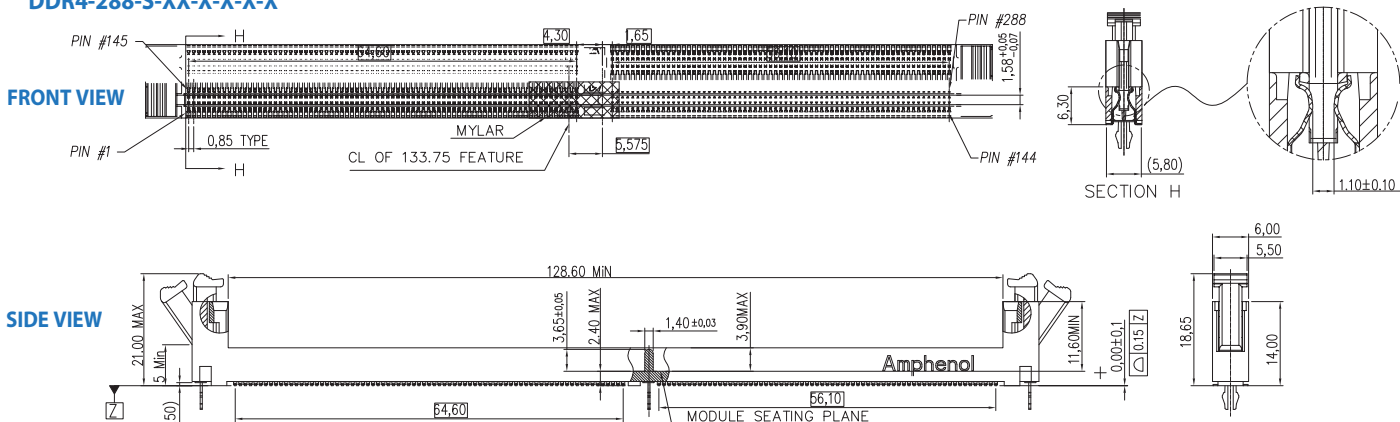
Dimensions:

DDR4-288-V-XX-X-X-T-X



All drawings are measured in millimeters (mm).

DDR4-288-S-XX-X-X-X-X



* Please visit amphenolcanada.com to find drawings for other products in this series.